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TABLE OF CONTENTS

Advanced Cooling for Power Electronics	1
<i>Sukhvinder S. Kang</i>	
Electromagnetic Modeling of EMI Input Filters	9
<i>Ivana Kovacevic, Andreas Musing, Thomas Friedli, Johann. W. Kolar</i>	
Calculating Transient Thermal Load of ECUs in Engine Compartment by Applying Simplified Physical Models	18
<i>M. Decker, T. Riepl</i>	
Comparative Evaluation of Individual and Coupled Inductor Arrangements for Input Filters of PV Inverter Systems	24
<i>Bernardo Cougo, Thomas Friedli, David O. Boillat, Johann W. Kolar</i>	
Analysis and Reduction of Radiated EMI of Power Modules	32
<i>Andre Domurat-Linde, Eckart Hoene</i>	
The Performance of the Multilevel Converter Topologies for PV Inverter	38
<i>Yugo Kashihara, Jun-ichi Itoh</i>	
Integrated Power Electronics Interface for Plug-In Hybrid Electric Vehicle Applications	44
<i>Omar Hegazy, Joeri Van Mierlo, Philippe Lataire, Mohamed El Baghdadi</i>	
Reliability of Power Electronics Under Thermal Loading	50
<i>Patrick McCluskey</i>	
Reliability Driven Virtual Prototyping of Power Electronic Equipment - A Case Study	58
<i>Till Huesgen, Gernot J Riedel, Uwe Drofenik</i>	
New Methods Help Better Evaluate Risks Via Simulation	63
<i>Angelika Schingale, Daniela Wolf, Andreas Schiebl, Marius Tarnovetchi</i>	
Separating Failure Modes in Power Cycling Tests	68
<i>Ralf Schmidt, Uwe Scheuermann</i>	
In-situ Bond Wire and Solder Layer Health Monitoring Circuit for IGBT Power Modules	74
<i>Bing Ji, Volker Pickert, Bashar Zahawi</i>	
Thermal Networks for Time-Variant Cooling Systems: Modeling Approach and Accuracy Requirements for Lifetime Prediction	80
<i>Thomas Gradinger, Gernot Riedel</i>	
Lifetime Evaluation of IGBT Power Modules Applying a Nonlinear Saturation Voltage Observer	86
<i>Dennis Wagenitz, Andreas Hambrecht, Sibylle Dieckerhoff</i>	
Influence of Thermal Cross-couplings on Power Cycling Lifetime of IGBT Power Modules	91
<i>Tilo Poller, Salvatore D'Arco, Magnar Hernes, Josef Lutz</i>	
Combined Reliability Testing: An Approach to Assure Reliability under Complex Loading Conditions	97
<i>Olaf Wittler, Johannes Jaeschke, Olaf Bochow-Neß, Andreas Middendorf, Klaus-Dieter Lang</i>	
System Approach for Reliability of Low-power Power Electronics; How to Break Down into Their Constructed Parts	104
<i>S. Tarashioon, W. D. van Driel, G. Q Zhang</i>	
Influence of Bonding Parameters on the Reliability of Heavy Wire Bonds on Power Semiconductors	109
<i>Jens Goehre, Ute Geißler, Martin Schneider-Ramelow, Klaus-Dieter Lang</i>	
Microstructural and Mechanical Characterization of Ceramic Substrates with Different Metallization for Power Applications	115
<i>Bianca Bottge, Sandy Klengel, Jan Schischka, Georg Lorenz, Heiko Knoll</i>	
Reliability of Large Area Solder Joints within IGBT Modules: Numerical Modeling and Experimental Results	121
<i>G. J. Riedel, R. Schmidt, C. Liu, H. Beyer, I. Alapera</i>	
Effect of Input Power Interruptions on Power Electronics Reliability	127
<i>J. Pippola, L. Frisk, K. Kokko, J. Kiilunen, T. Marttila</i>	
Efficient Nonlinear Inductors for PV Inverters and Active PFC	133
<i>Alexander Stadler, Christof Gulden</i>	
A 150 kW Medium Frequency Transformer Optimized for Maximum Power Density	137
<i>Uwe Drofenik</i>	
Integration of Leakage Inductance in Tape Wound Core Transformers for Dual Active Bridge Converters	143
<i>Bernardo Cougo, Johann W. Kolar</i>	

Laminated Bus Bar Structure for Low Induced Noise	149
<i>Zennosuke Ariga, Keiji Wada</i>	
Integrated, High-Frequency DC-DC Converter Technologies Leading to Monolithic Power Conversion	155
<i>Ashraf W. Lotfi, Qiang Li, Fred C. Lee</i>	
Micro-fabricated Thin-film Inductors for on-chip Power Conversion	163
<i>Daniel V. Harburg, Xuehong Yu, Florian Herrault, Christopher G. Levey, Mark G. Allen, Charles R. Sullivan</i>	
Radial-Anisotropy Thin-Film Magnetic Material for High-Power-Density Toroidal Inductors	169
<i>Jizheng Qiu, Charles R. Sullivan</i>	
An Improved Parasitic Capacitance Cancellation Method for Planar Differential Mode Inductor in EMI Filters	175
<i>Wenhua Tan, Xavier Margueron, Thierry Duquesne, Nadir Idir</i>	
Hybrid Integrated EMC filter for CM and DM EMC Suppression in a DC-DC Power converter	181
<i>Marwan Ali, Eric Laboure, Francois Costa, Bertrand Revol, Cyrille Gautier</i>	
Integrated High Power Modules	187
<i>C. Mark Johnson, Alberto Castellazzi, Robert Skuriat, Paul Evans, Jianfeng Li, Pearl Agyakwa</i>	
Alternative Lead Free Die Attach for Power Module Packaging	197
<i>Jean Michel Morelle, Ky Lim Tan, Laurent Vivet, Renan Leon, Serge Lavrentieff</i>	
Reducing Parasitic Electrical Parameters with a Planar Interconnection Packaging Structure	204
<i>Zhenxian Liang, Puqi Ning, Fred Wang, Laura Marlino</i>	
New Assembly and Interconnect Technologies for Power Modules	210
<i>K. Guth, N. Oeschler, L. Bower, R. Speckels, G. Strotmann, N. Heuck, S. Krasel, A. Ciliox</i>	
Direct Cooled Modules - Integrated Heat Sinks	215
<i>Olaf Hohlfeld, Alexander Herbrandt</i>	
Stacked Substrates for High Voltage Applications	219
<i>Olaf Hohlfeld, R. Bayerer, Th. Hunger, H. Hartung</i>	
SiC and GaN Devices - Competition or Coexistence?	223
<i>Nando Kaminski, Oliver Hilt</i>	
Holistic Approach to Maximize Power Density in Industrial Inverter Designs	234
<i>Martin Schulz, Liliana De Lillo, Lee Empringham</i>	
Integrated Anti-Short-Circuit Safety Circuit in CMOS SOI for Normally-On JFET	240
<i>Khalil El Falahi, Fabien Dubois, Dominique Bergogne, Damien Risaletto, Bruno Allard</i>	
Electrical Analysis and Packaging Solutions for High-Current Fast-Switching SiC Components	245
<i>Michel Mermet-Guyennet, Alberto Castellazzi, Joseph Fabre, Philippe Ladoux</i>	
Design of an Integrated Power Converter in Wide Band Gap for Harsh Environments	251
<i>Jean-Francois Mogniotte, Dominique Tournier, Pascal Bevilacqua, Philippe Godignon, Dominique Planson</i>	
Reducing Expenditure with Cooling in Renewable Power Conversion Systems with Innovative SiC Switches	257
<i>Samuel Araujo, Peter Zacharias</i>	
3-Dimensional, Solder-Free Interconnect Technology for High-Performance Power Modules	263
<i>Bassem Mouawad, Cyril Buttay, Maher Soueidan, Herve Morel, Bruno Allard, Damien Fabregue, Vincent Bley</i>	
Reliability of Silver Sintering on DBC and DBA Substrates for Power Electronic Applications	269
<i>Silke Kraft, Andreas Schletz, Martin Marz</i>	
Low-pressure (< 5 MPa) Low-temperature Joining of Large-area Chips on Copper Using Nanosilver Paste	275
<i>Hanguang Zheng, Jesus Calata, Khai Ngoa, Susan Luo, Guo-Quan Lu</i>	
Sintered Silver Joint Strength Dependence on Substrate Topography and Attachment Pad Geometry	281
<i>Andrew A. Wereszczak, Daniel J. Vuono, Zhenxian Liang, Ethan E. Fox</i>	
Thermo Mechanical Reliability of Low-temperature Low-pressure Die Bonding Using Thin Ag Flake Pastes	287
<i>Soichi Sakamoto, Katuaki Sukanuma</i>	
Planar Interconnect Technology for Power Module System Integration	289
<i>K. Weidner, M. Kaspar, N. Seliger</i>	
Reliability of Planar SKiN Interconnect Technology	294
<i>Uwe Scheuermann</i>	
SiC Device and Power Module Technologies for Environmentally Friendly Vehicles	302
<i>Kimimori Hamada</i>	
Control of Primary Active Rectifiers of Traction Converter with Medium-Frequency Transformer: Benefits of Control Unit Combin-ing DSP and FPGA	308
<i>Dusan Janik, Zdenek Peroutka, Jan Molnar, Tomas Komrska, Jan Zak</i>	
Scalable High Insulation Power Supply for Medium Voltage Power Converters	313
<i>Iosu Aizpuru, Jose Maria Canales, Jesus Fernandez</i>	

Amplitude Modulated Resonant Push-Pull Driver for Piezoelectric Transformers in Switching Power Applications.....	319
<i>Holger Schwarzmann, Tobias Erbacher, Anton J. Bauer, Heiner Ryssel, Lothar Frey</i>	
Asymmetrical Parasitic Inductance Utilized for Switching Loss Reduction in Power Modules	324
<i>Michael Frisch, Temesi Erno</i>	
Thermal Management Concepts for Power Sandwich Industrial Drive	330
<i>I. Josifovic, J. Popovic-Gerber, J.A. Ferreira</i>	
Reliable Integration of Double-Sided Cooled Stacked Power Switches based on 70 μm Thin IGBTs and Diodes	336
<i>J. F. Li, A. Castellazzi, A. Solomon, C. M. Johnson</i>	
Influence of Baseplate Design on Cooling Performance and Reliability	342
<i>Kai Kriegel, Thomas Komma, Walter Kiffe, Svetlana Levchuk, Johann Otto</i>	
Comparison Between Electromagnetic and Thermal Stress Induced by Direct Current Flow in IGBT Bond Wires.....	347
<i>H. Medjahed, P.-E. Vidal, B. Nogarede</i>	
Centrifugal Formulation of Percolating Thermal Underfills for Flip-Chip Applications	353
<i>J. Zurcher, J. Goicochea, K. Matsumoto, B. Michel, T. Brunschweiler</i>	
Development and Testing of Cold Gas Sprayed Circuit Boards for Power Electronics Applications	359
<i>Eugen Rastjagaev, Jurgen Wilde, Bernhard Wielage, Thomas Grund</i>	
Development of High Temperature Packaging Technologies for SiC Power Devices based on Finite Elements Simulations and Experiments: Thermal Approach.....	365
<i>L. Zhang, S. Azzopardi, A. Gracia, E. Woirgard, J-Y. Deletage</i>	
Mixed-Signal and Smart-Power Capable Hybrid Structured ASIC for Cost-Aware Single-Chip Integration of Industrial Applications	371
<i>Yipin Zhang, Cor Scherjon, Joachim N. Burghartz</i>	
Design Considerations of Very Low Profile Coupled Inductors for Flexible Photovoltaic Module.....	375
<i>Z. Ouyang, M. Acanski, J. Popovic, J. A. Ferreira, O. C. Thomsen, M. A. E. Andersen</i>	
Design of a PCB Rogowski Coil based on the PEEC Method	383
<i>T. Guillod, D. Gerber, J. Biela, A. Musing</i>	
Wafer-level Fabrication of High-power-density MEMS Passives based on Silicon Molding Technique	389
<i>Jiping Li, Khai D. T. Ngo, Guo-Quan Lu, Huikai Xie</i>	
A Hybrid Hydraulic Piezo Actuator and its Control for Camless Internal Combustion Engines	394
<i>Paolo Mercorelli, Nils Werner, Udo Becker, Horst Harndorf</i>	
Reliability Comparison of a Dual Boost and a Triangular Current Mode Resonant-Transition PFC Converter Topology.....	400
<i>S. Allemann, J. Biela, M. Held</i>	
EMI Prediction of Power Converters using Switching Waveform Analysis.....	405
<i>Sebastian Schulz, Peter Kanschat, Andreas Lindemann</i>	
Consideration of Electrical Parasitics in Conjunction with Thermal Behaviour of Power Semiconductor Components	410
<i>Stefan Forster, Andreas Lindemann</i>	
GaN-over-Si: The Promising Technology for Power Electronics in Automotive	416
<i>Cherif Assad, Herve Mureau</i>	
How to Control SiC BJT with High Efficiency?.....	420
<i>Luyu Wang, Hans Bangtsson</i>	
Application of eGaN FETs for Highly Efficient Radio Frequency Power Amplifier	424
<i>D. Cucak, M. Vasic, O. Garcia, J. A. Oliver, P. Alou, J. A. Cobos</i>	
Sinter Materials for Broad Process Windows in DCB Packages - Concepts and Results.....	430
<i>Wolfgang Schmitt, Sebastian Fritzsche, Muriel Thomas</i>	
Quality Evaluation for Silver Sintering Layers in Power Electronic Modules	436
<i>Jacek Rudzki, Lars Jensen, Max Poech, Lothar Schmidt, Frank Osterwald</i>	
Evaluation of Silver-sintering Die Attach	442
<i>W. Sabbah, R. Riva, S. Hascot, C. Buttay, S. Azzopardi, E. Woirgard, D. Planson, B. Allard, R. Meuret</i>	
Extreme Efficiency Power Electronics	449
<i>J. W. Kolar, F. Krismer, Y. Lobsiger, J. Muhlethaler, T. Nussbaumer, J. Minibock</i>	
Author Index	